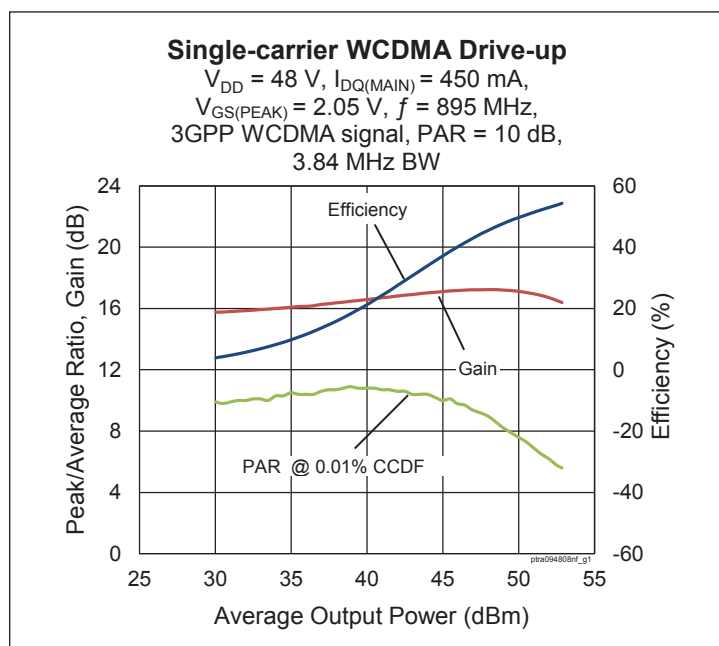


Thermally-Enhanced High Power RF LDMOS FET 480 W, 48 V, 859 – 960 MHz

Description

The PTRA094808NF is a 480-watt LDMOS FET intended for use in multi-standard cellular power amplifier applications in the 859 to 960 MHz frequency band. Features include input and output matching, high gain and thermally-enhanced package with earless flanges. Manufactured with Infineon's advanced LDMOS process, this device provides excellent thermal performance and superior reliability.

PTRA094808NF
Package PG-HBSOF-6-2



Features

- Broadband internal input and output matching
- Asymmetrical design
 - Main : $P_{1dB} = 210\text{ W Typ}$
 - Peak : $P_{1dB} = 340\text{ W Typ}$
- Typical Pulsed CW performance, 896 MHz, 48 V, Doherty configuration
 - Output power at $P_{1dB} = 300\text{ W}$
 - Output power at $P_{3dB} = 420\text{ W}$
 - Efficiency = 53%
 - Gain = 17.5 dB
- Capable of handling 10:1 VSWR @ 48 V, 100 W (CW) output power
- Integrated ESD protection
- Human Body Model class 1C (per ANSI/ESDA/ JEDEC JS-001)
- Low thermal resistance
- Pb-free and RoHS compliant

RF Characteristics

Single-carrier WCDMA Specifications (tested in Infineon Doherty production test fixture)

$V_{DD} = 48\text{ V}$, $I_{DQ} = 450\text{ mA}$, $V_{GS(PEAK)} = 2.05\text{ V}$, $P_{OUT} = 87\text{ W avg}$, $f = 895\text{ MHz}$, 3GPP signal, channel bandwidth = 3.84 MHz, peak/average = 10 dB @ 0.01% CCDF

Characteristic	Symbol	Min	Typ	Max	Unit
Linear Gain	G_{ps}	16.5	17.5	—	dB
Drain Efficiency	η_D	48.5	52.5	—	%
Adjacent Channel Power Ratio	ACPR	—	-30.5	-26.5	dBc
Output PAR@0.01% CCDF	OPAR	7.1	7.5	—	dB

All published data at $T_{CASE} = 25^\circ\text{C}$ unless otherwise indicated

ESD: Electrostatic discharge sensitive device—observe handling precautions!

DC Characteristics (each side)

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}$, $I_{DS} = 10\text{ mA}$	$V_{(BR)DSS}$	105	—	—	V
Drain Leakage Current	$V_{DS} = 48\text{ V}$, $V_{GS} = 0\text{ V}$	I_{DSS}	—	—	1	μA
	$V_{DS} = 105\text{ V}$, $V_{GS} = 0\text{ V}$	I_{DSS}	—	—	10	μA
Gate Leakage Current	$V_{GS} = 14\text{ V}$, $V_{DS} = 0\text{ V}$	I_{GSS}	—	—	1	μA
On-State Resistance (Main)	$V_{GS} = 10\text{ V}$, $V_{DS} = 0.1\text{ V}$	$R_{DS(on)}$	—	0.08	—	Ω
	(Peak) $V_{GS} = 10\text{ V}$, $V_{DS} = 0.1\text{ V}$	$R_{DS(on)}$	—	0.05	—	Ω
Operating Gate Voltage (Main)	$V_{DS} = 48\text{ V}$, $I_{DQ} = 0.45\text{ A}$	V_{GS}	3	3.5	4	V
	(Peak) $V_{DS} = 48\text{ V}$, $I_{DQ} = 0\text{ A}$	V_{GS}	—	2.05	—	V

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	105	V
Gate-Source Voltage	V_{GS}	−6 to +12	V
Operating Voltage	V_{DD}	0 to +55	V
Junction Temperature	T_J	225	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	−65 to +150	$^{\circ}\text{C}$

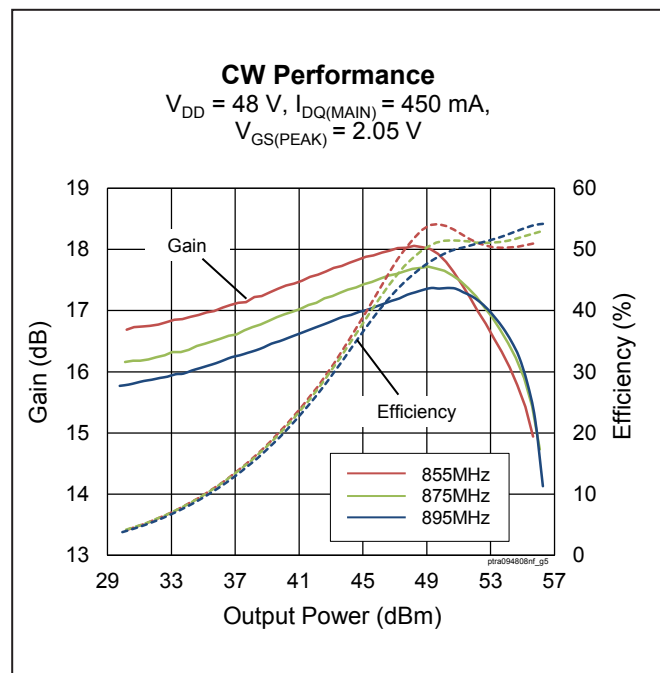
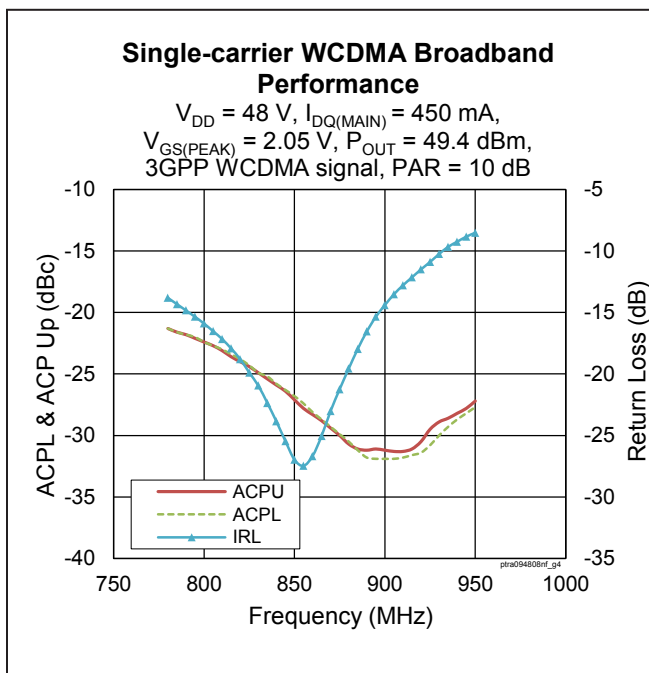
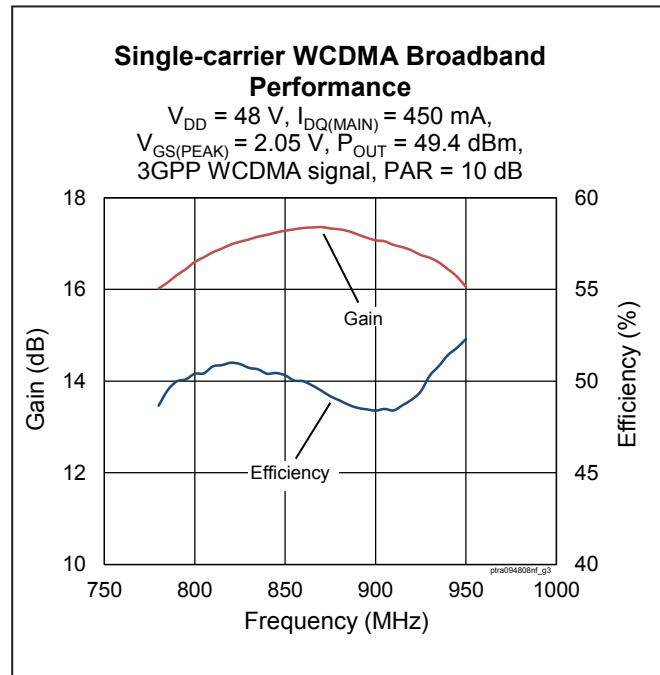
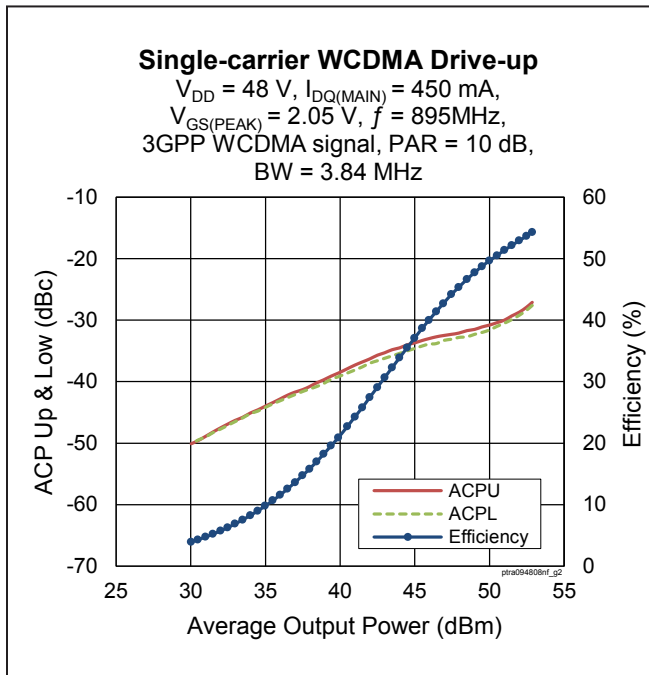
Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance (Main, $T_{CASE} = 70^{\circ}\text{C}$, 87.1 W CW)	$R_{\theta JC}$	0.51	$^{\circ}\text{C/W}$

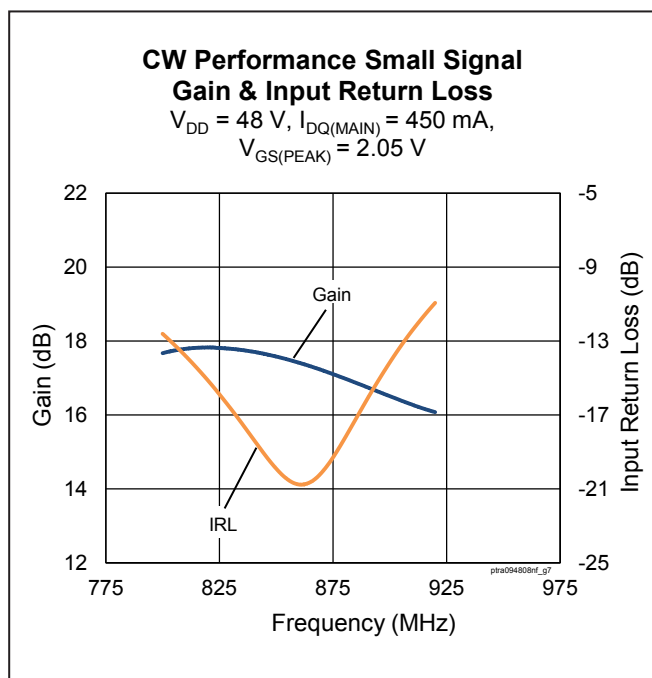
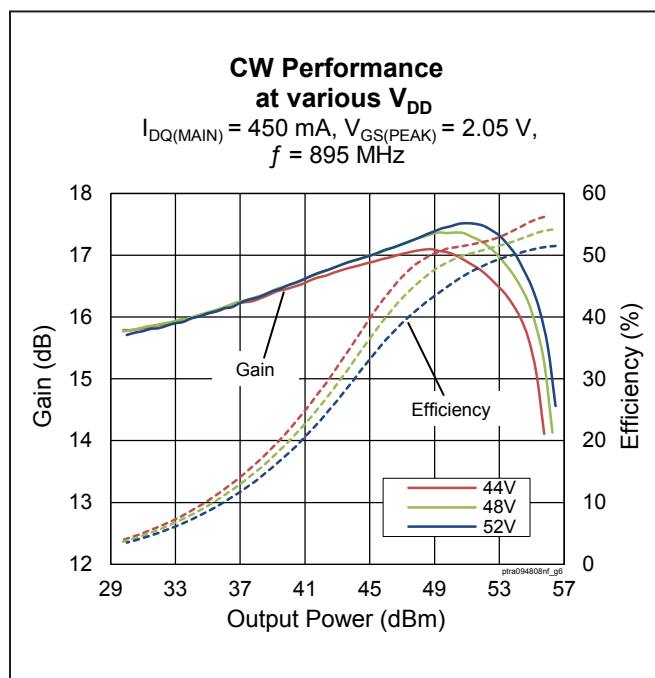
Ordering Information

Type and Version	Order Code	Package Description	Shipping
PTRA094808NF V1 R5	PTRA094808NFV1R5XUMA1	PG-HBSOF-6-2	Tape & Reel, 500 pcs

Typical RF Performance (data taken in production test fixture)



Typical RF Performance (cont.)



Load Pull Performance

Main Side Load Pull Performance – Pulsed CW signal: 10 μ sec, 10% duty cycle, $V_{DD} = 48$ V, $I_{DQ} = 350$ mA, class AB

		P_{1dB}									
		Max Output Power					Max Drain Efficiency				
Freq [MHz]	Z_s [Ω]	Z_L [Ω]	Gain [dB]	P_{1dB} [dBm]	P_{1dB} [W]	η_D [%]	Z_L [Ω]	Gain [dB]	P_{1dB} [dBm]	P_{1dB} [W]	η_D [%]
865	1.4-j4.1	1.93-j1.35	20.25	53.40	219	57.4	4.16-j0.34	22.1	51.50	141	67.2
880	1.6-j4.65	1.67-j1.24	19.8	53.40	219	54.6	4.0-j0.5	22.1	51.50	141	67.7
895	2.0-j4.33	1.87-j1.62	20	53.37	217	56.7	4.08-j0.33	22	51.37	137	67.6

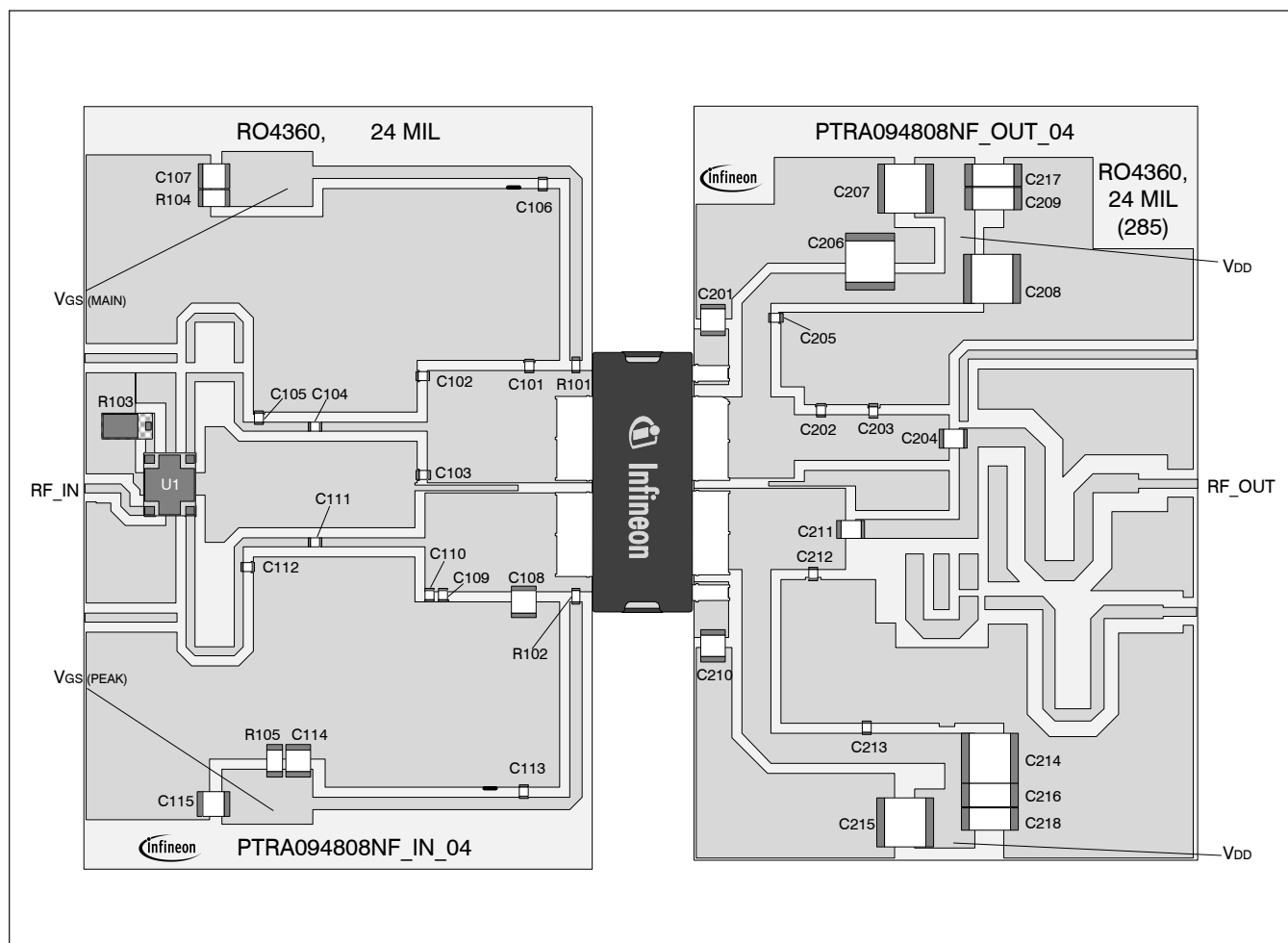
		P_{3dB}									
		Max Output Power					Max Drain Efficiency				
Freq [MHz]	Z_s [Ω]	Z_L [Ω]	Gain [dB]	P_{3dB} [dBm]	P_{3dB} [W]	η_D [%]	Z_L [Ω]	Gain [dB]	P_{3dB} [dBm]	P_{3dB} [W]	η_D [%]
865	1.4-j4.1	2.09-1.87	18.4	54.30	270	61.8	3.8+0	20	52.62	182	69.1
880	1.6-j4.65	1.87-1.73	18	54.20	263	58.7	3.56+0.05	19.85	52.67	184	69.5
895	2.0-j4.33	1.81-1.78	17.9	54.20	263	59.1	3.33+0.04	19.73	52.65	184	69.43

Peak Side Load Pull Performance – Pulsed CW signal: 10 μ sec, 10% duty cycle, $V_{DD} = 48$ V, $V_{GS(PEAK)} = 2$ V, class C

		P_{1dB}									
		Max Output Power					Max Drain Efficiency				
Freq [MHz]	Z_s [Ω]	Z_L [Ω]	Gain [dB]	P_{1dB} [dBm]	P_{1dB} [W]	η_D [%]	Z_L [Ω]	Gain [dB]	P_{1dB} [dBm]	P_{1dB} [W]	η_D [%]
865	1.57-j3.71	1.17-j1.97	16	55.80	380	58.8	1.01-j0.55	17.1	53.17	207	71.1
880	1.58-j3.55	1.15-j3.55	16	55.70	372	59.0	1.08-j0.83	17	53.70	234	70.9
895	1.82-3.82	1.14-j2.05	16	55.84	384	60.9	1.11-j1.04	16.9	54.10	257	71.1

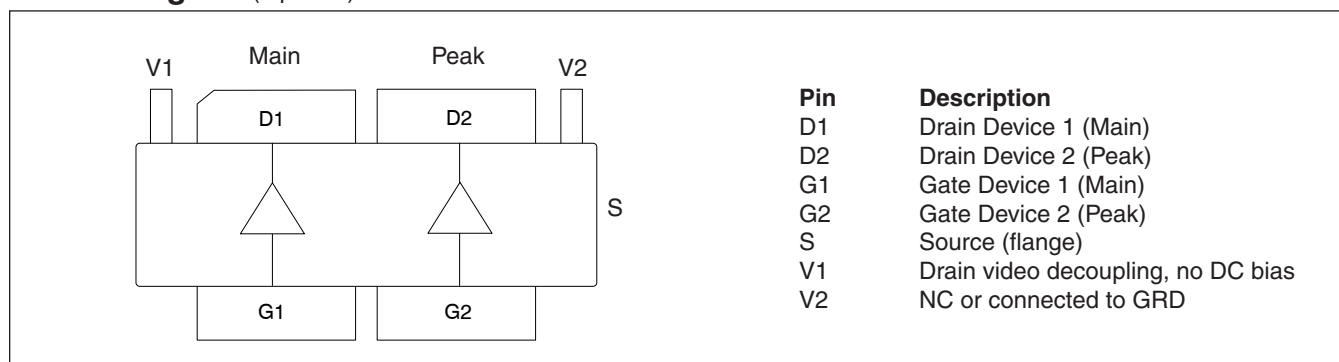
		P_{3dB}									
		Max Output Power					Max Drain Efficiency				
Freq [MHz]	Z_s [Ω]	Z_L [Ω]	Gain [dB]	P_{3dB} [dBm]	P_{3dB} [W]	η_D [%]	Z_L [Ω]	Gain [dB]	P_{3dB} [dBm]	P_{3dB} [W]	η_D [%]
865	1.57-j3.71	1.2-1.97	14	56.68	466	61.9	1.17-0.93	15.1	55.12	325	71.2
880	1.58-j3.55	1.32-2.11	13.8	56.46	443	60.6	1.15-1.05	15	55.00	316	70.7
895	1.82-3.82	1.19-2.09	13.9	56.59	456	62.4	1.05-1.04	14.8	54.72	296	71.0

Reference Circuit, 869 – 894 MHz



Reference circuit assembly diagram (not to scale)

Pinout Diagram (top view)



Reference Circuit (cont.)

Reference Circuit Assembly

DUT	PTRA094808NF V1
Test Fixture Part No.	LTA/PTRA094808NF V1
PCB	Rogers 4360, 0.609 mm [0.024"] thick, 2 oz. copper, $\epsilon_r = 6.15$, $f = 869 - 894$ MHz
Find Gerber files for this test fixture on the Infineon Web site at http://www.infineon.com/rfpower	

Components Information

Component	Description	Manufacturer	P/N
Input			
C101	Capacitor, 6.8 pF	ATC	ATC600F6R8BT250T
C102	Capacitor, 2.7 pF	ATC	ATC600F2R7BT250T
C103, C105	Capacitor, 1.8 pF	ATC	ATC600F1R8BT250T
C104, C111	Capacitor, 33 pF	ATC	ATC600F330JT250T
C106, C113	Capacitor, 68 pF	ATC	ATC600F680JT250T
C107, C114, C115	Capacitor, 10 μ F	Taiyo Yuden	UMK325C7106MM-T
C108	Capacitor, 8.2 pF	ATC	ATC100B8R2BT500XB
C109	Capacitor, 2.0 pF	ATC	ATC600F2R0BT250T
C110	Capacitor, 1.0 pF	ATC	ATC600F1R0BT250T
C112	Capacitor, 3.3 pF	ATC	ATC600F3R3BT250T
R101, R102	Resistor, 5.6 ohms	Panasonic Electronic Components	ERJ-8RQJ5R6V
R103	Resistor, 50 ohms	ANAREN	C16A50Z4
R104, R105	Resistor, 1000 ohms	Panasonic Electronic Components	ERJ-8GEYJ102V
U1	Hybrid Coupler	CEMAX	CMX09Q02
Output			
C201, C210	Capacitor, 10 μ F	Taiyo Yuden	UMK325C7106MM-T
C202	Capacitor, 10 pF	ATC	ATC600F100JT250T
C203	Capacitor, 1.5 pF	ATC	ATC600F1R5CT250T
C204	Capacitor, 20 pF	ATC	ATC100B200JT500XB
C205	Capacitor, 68 pF	ATC	ATC600F680JT250T
C206, C207, C208, C214, C215	Capacitor, 10 μ F, 50V	Taiyo Yuden	UMK325C7106MM-T
C209, C216, C217, C218	Capacitor, 10 μ F, 100V	TDK Corporation	C5750X7S2A106M230KB
C211	Capacitor, 47 pF	ATC	ATC100B470JT500XB
C212	Capacitor, 12 pF	ATC	ATC600F120JT250T
C213	Capacitor, 47 pF	ATC	ATC600F470JT250T

Package Outline Specifications

Package PG-HBSOF-6-2 (top view)

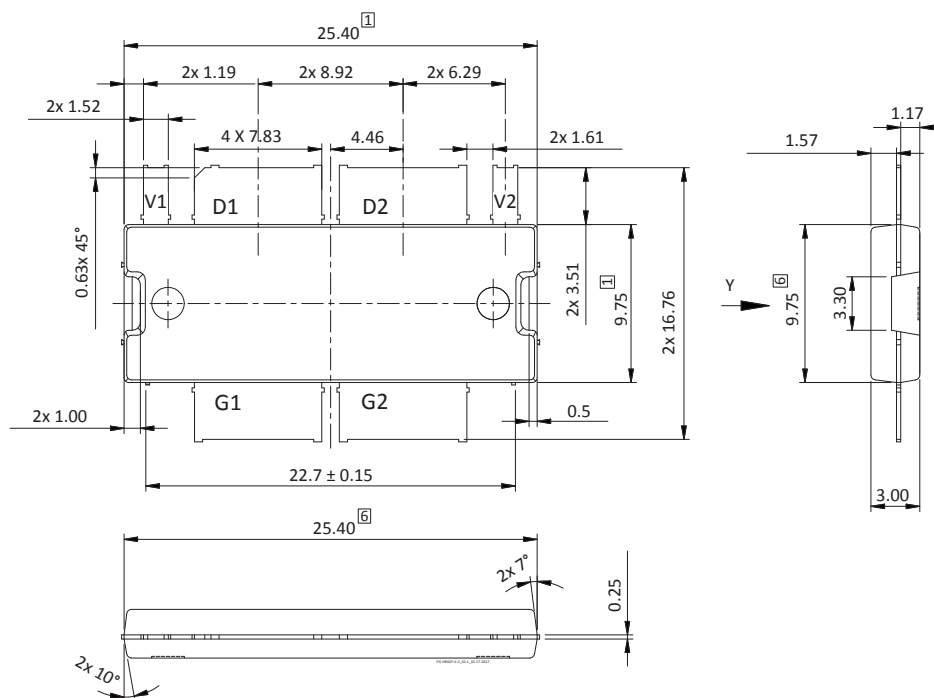


Diagram Notes—unless otherwise specified:

1. Mold/dam bar/metal protrusion of 0.30 mm max per side not included.
2. Metal protrusions are connected to source and shall not exceed 0.10 mm max.
3. Fillets and radii: all radii are 0.3 mm max.
4. Interpret dimensions and tolerances per ISO 8015.
5. Dimensions are mm.
6. Does not include mold/dam bar and metal protrusion.
7. Exposed metal surface is tin-plated, may not be covered by mold compound.
8. All tolerances ± 0.1 mm unless specified otherwise.
9. All metal surfaces are tin-plated, except area of cut.
10. Lead thickness: 0.25 mm.
11. Pins: D1, D2 = drain; G1, G2 = gate; S = source; V1 = drain video decoupling, no DC Bias, V2 = NC or connected to GRD

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Package Outline Specifications

Package PG-HBSOF-6-2 (bottom view)

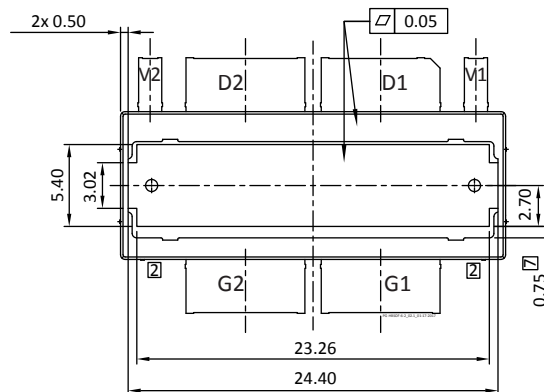


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Revision History

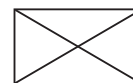
Revision	Date	Data Sheet Type	Page	Subjects (major changes since last revision)
01	2016-09-30	Advance	All	Data Sheet reflects advance specification for product development
02	2017-04-28	Production	All	Data Sheet reflects released product specification
03	2017-08-21	Production	6, 7	Updated PCB layout and components information

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highpowerRF@infineon.com

To request other information, contact us at:
+1 877 465 3667 (1-877-GO-LDMOS) USA
or +1 408 776 0600 International



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